

Description

These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- ◆ 30V,62A, $R_{DS(on),max} = 5.2\text{m}\Omega$ @ $V_{GS} = 10\text{V}$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

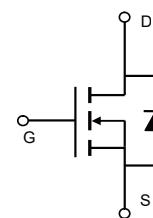
Product Summary

V_{DSS}	30V
$R_{DS(on),max}$ @ $V_{GS}=10\text{V}$	5.2m Ω
I_D	62A

Pin Configuration



TO-252



Schematic

Absolute Maximum Ratings

 $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	30	V
Continuous drain current ($T_c = 25^\circ\text{C}$)	I_D	62	A
($T_c = 100^\circ\text{C}$)		38	A
Pulsed drain current ¹⁾	I_{DM}	186	A
Gate-Source voltage	V_{GSS}	± 20	V
Avalanche energy ²⁾	E_{AS}	16.2	mJ
Power Dissipation	P_D	32	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.9	°C/W
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	80	°C/W

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Reel
VST03N052-T2	TO-252	VST03N052-T2	2500

Electrical Characteristics

T_J = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250μA	30	---	---	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.7	2.5	V
Drain-source leakage current	I _{DSS}	V _{DS} =30 V, V _{GS} =0V	---	---	1	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =20 V, V _{DS} =0 V	---	---	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-20 V, V _{DS} =0 V	---	---	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =20 A	---	4.2	5.2	mΩ
		V _{GS} =4.5 V, I _D =15 A	---	6.5	9	mΩ
Forward transconductance	g _{fs}	V _{DS} =5V , I _D =20A	---	66	---	S
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, F = 1MHz	---	1115	---	pF
Output capacitance	C _{oss}		---	437	---	
Reverse transfer capacitance	C _{rss}		---	56	---	
Turn-on delay time	t _{d(on)}	V _{DD} = 15V, V _{GS} =10V, I _D = 20A R _G =3.3Ω	---	7.1	---	ns
Rise time	t _r		---	19	---	
Turn-off delay time	t _{d(off)}		---	19.3	---	
Fall time	t _f		---	3.4	---	
Gate resistance	R _g	V _{GS} =0 V, V _{DS} =0 V, F=1MHz	---	1.6	---	Ω
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DS} =15V, I _D =20A, V _{GS} = 10 V	---	2.9	---	nC
Gate to drain charge	Q _{gd}		---	3.5	---	
Gate charge total	Q _g		---	16.5	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I _S		---	---	26.5	A
Pulsed Source Current ³⁾	I _{SM}		---	---	79.5	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A, T _J =25°C	---	---	1.2	V

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=18A, Starting T_J=25°C.

3: Pulse Test: Pulse Width ≤300 μ s, Duty Cycle≤2%.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

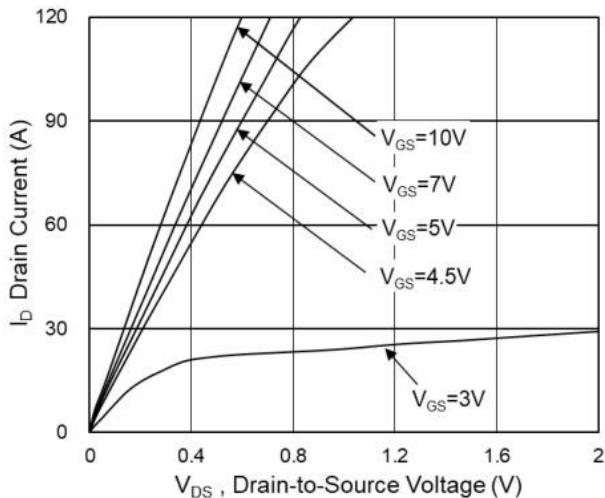


Figure 2. Transfer Characteristics

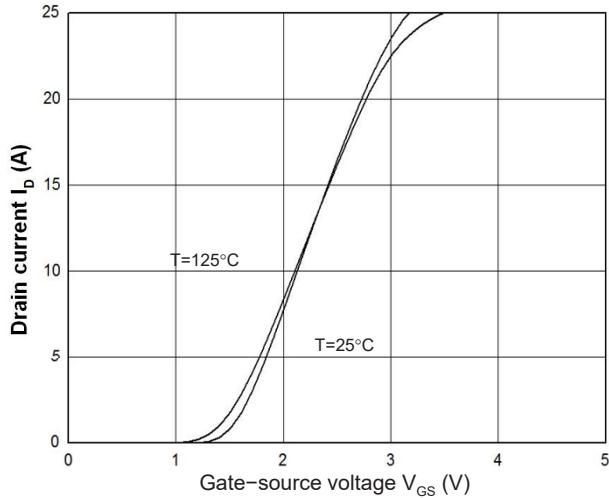


Figure 3. Capacitance Characteristics

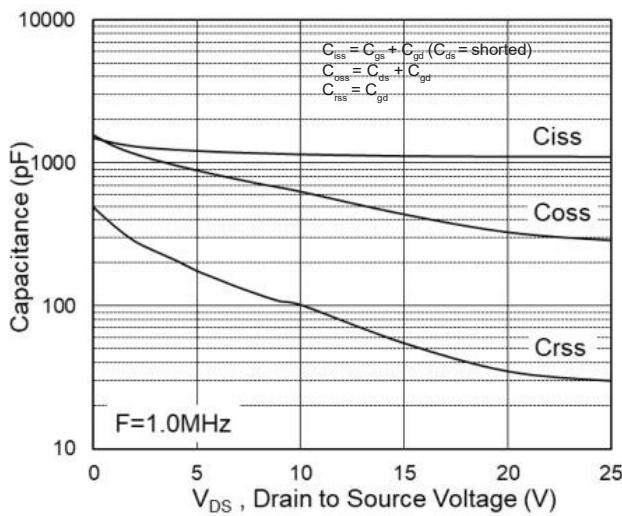


Figure 4. Gate Charge Waveform

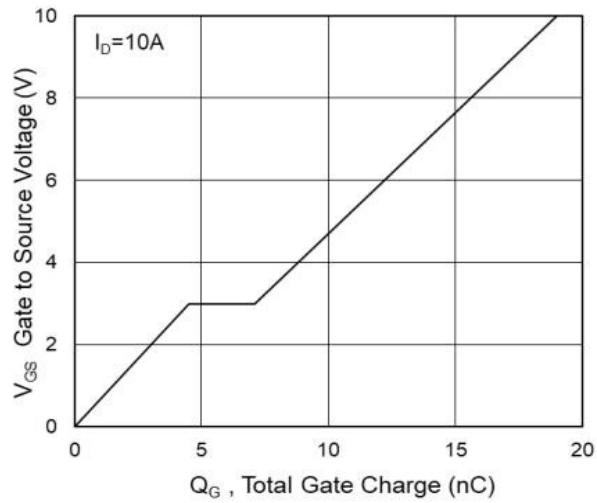


Figure 5. Body-Diode Characteristics

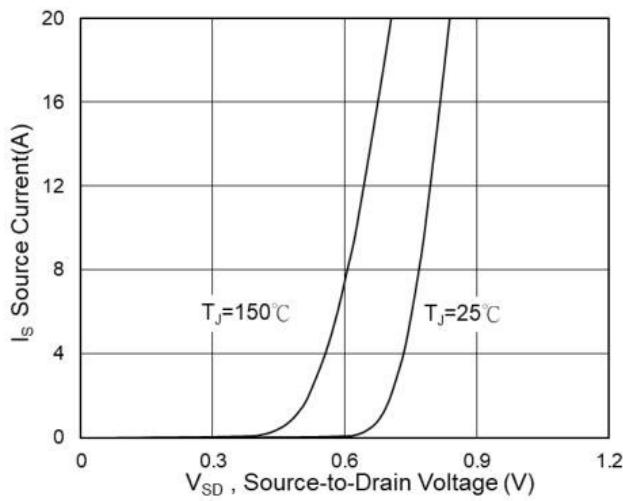


Figure 6. Rdson-Drain Current

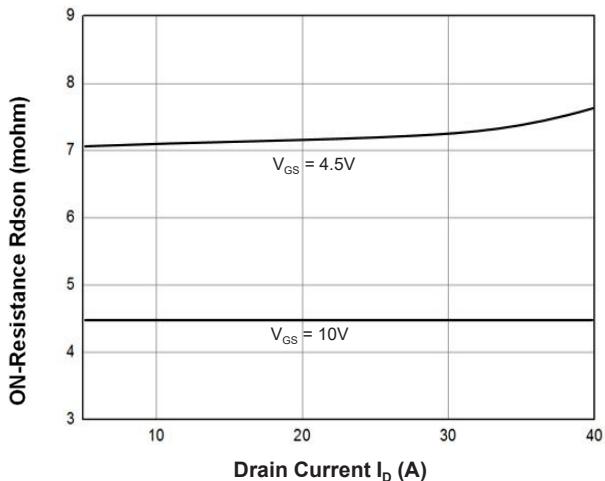


Figure 7. Rdson-Junction Temperature

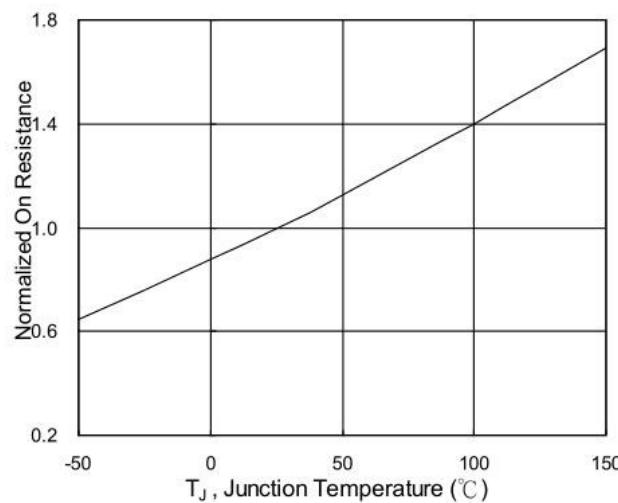


Figure 8. $V_{GS(th)}$ -Junction Temperature

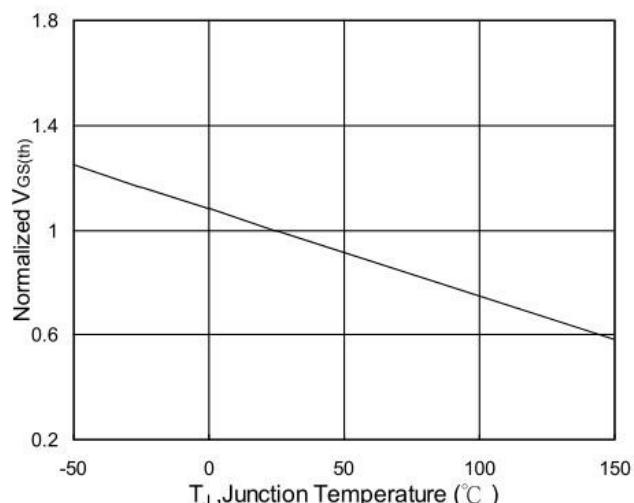


Figure 9. On-Resistance vs. Gate-to-Source voltage

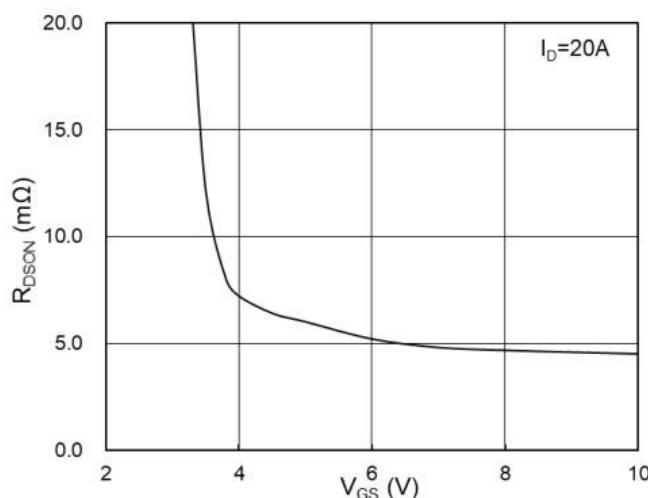


Figure 10: Safe Operating Area

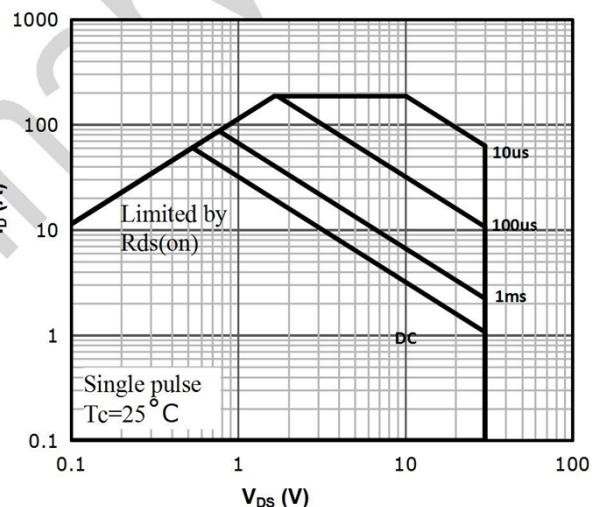
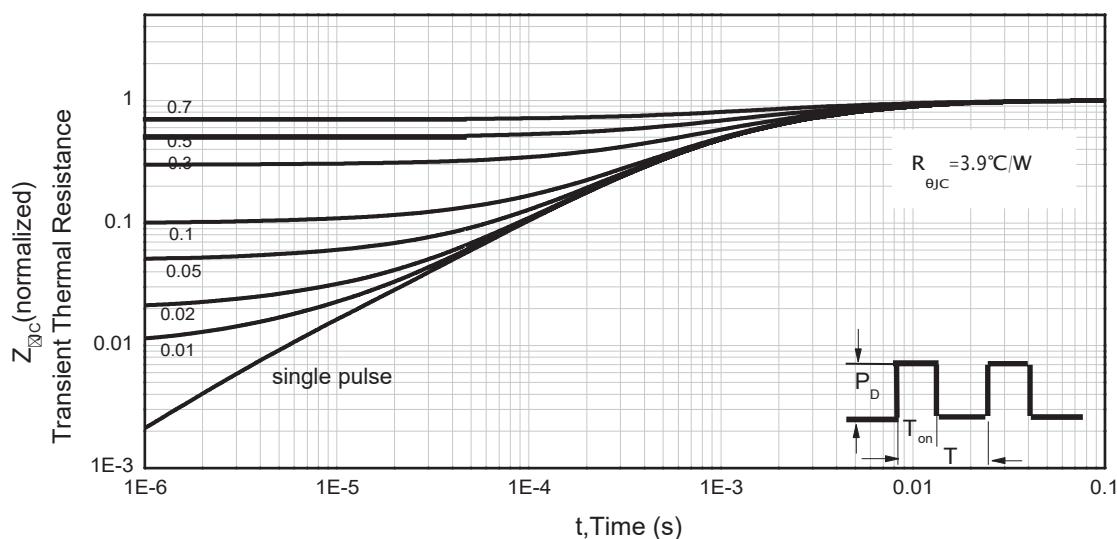
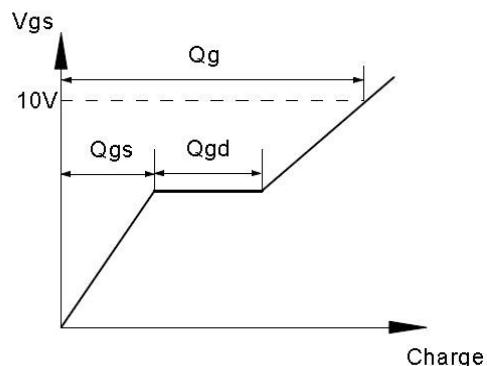
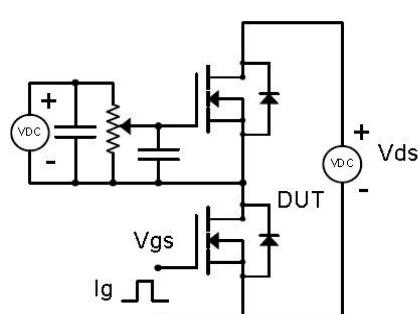


Figure 11. Normalized Maximum Transient Thermal Impedance (R_{thJC})

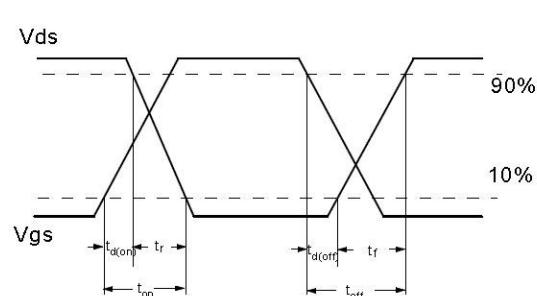
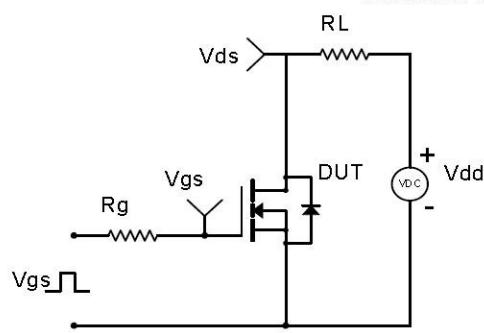


Test Circuit & Waveform

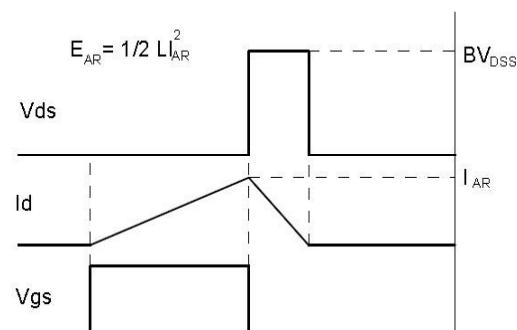
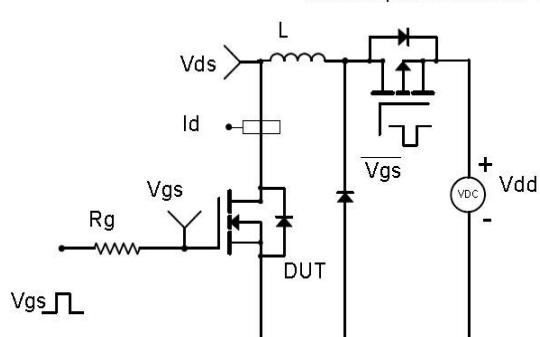
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

